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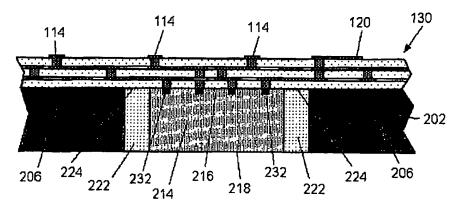
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For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: MICROELECTRONIC PACKAGE HAVING BUMPLESS LAMINATED INTERCONNECTION LAYER



(57) Abstract: A microelectronic device fabrication technology that places at least one microelectronic die within at least one opening in a microelectronic package core and secures the microelectronic die/dice within the openings(s) with an encapsulation material, that encapsulates at least one microelectronic die within an encapsulation material without a microelectronic package core, or that secures at least one microelectronic die within at least one opening in a heat spreader. A laminated interconnector of dielectric materials and conductive traces is then attached to the microelectronic die/dice and at least one of following: the encapsulation material, the microelectronic package core, and the heat spreader, to form a microelectronic device.





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A. CLASSIFICATION OF SUBJECT MATTER IPC 7 H01L23/538 H01L23/36 H01L23/498 H01L21/68 H01L21/60 According to International Patent Classification (IPC) or to both national classification and IPC B. FIELDS SEARCHED Minimum documentation searched (classification system followed by classification symbols) IPC 7 H01L Documentation searched other than minimum documentation to the extent that such documents are included. In the fields searched Electronic data base consulted during the International search (name of data base and, where practical, search terms used) EPO-Internal C. DOCUMENTS CONSIDERED TO BE RELEVANT Category ° Citation of document, with Indication, where appropriate, of the relevant passages Relevant to claim No. Χ US 5 497 033 A (FILLION RAYMOND A ET AL) 1,2,4, 5 March 1996 (1996-03-05) 11,13 Υ the whole document 3,5,9, 10,12, 14,15 χ EP 0 110 285 A (PRUTEC LTD) 6-8 13 June 1984 (1984-06-13) page 5, line 18-24; figure 2 14,15 US 5 384 955 A (GREMBAN BRADLEY S ET AL) 3,5,9, 31 January 1995 (1995-01-31) 10,12 column 2, line 57-59; figure 1F column 3, line 51-53 column 4, line 24-26 X Further documents are listed in the continuation of box C. Petent lamily members are listed in annex. Special categories of cited documents: "I" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the "A" document defining the general state of the art which is not considered to be of particular relevance "E" earlier document but published on or after the International filling date "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone "L" document which may throw doubts on priority claim(s) or which is ched to establish the publication date of another cliation or other special reason (as specified) "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art. "O" document referring to an oral disclosure, use, exhibition or document published prior to the international filing date but later than the priority date claimed "&" document member of the same patent family Date of the actual completion of the international search Date of mailing of the international search report 16 JUL 2003 19 May 2003 Name and mailing address of the ISA Authorized officer European Patent Office, P.B. 5818 Patentlaan 2 NL - 2280 HV Rijswijk Tel. (+31-70) 340-2040, Tx. 31 851 epo nl, Fax: (+31-70) 340-3016 Kästner, M

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citation of document, with indication where appropriate of the relevant	15
or accountant, that inclosuou, where appropriate, of the relevant passages	Relevant to claim No.
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column 4, line 65	24
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Box I. Observations where certain claims were found unsearchable (Continuation of Item 1 of first sheet)
This International Search Report has not been established in respect of certain claims under Article 17(2)(a) for the following reasons:
Claims Nos.: because they relate to subject matter not required to be searched by this Authority, namely:
2. Claims Nos.: because they relate to parts of the international Application that do not comply with the prescribed requirements to such an extent that no meaningful international Search can be carried out, specifically:
3. Claims Nos.: because they are dependent claims and are not drafted in accordance with the second and third sentences of Rule 6.4(a).
Box II Observations where unity of invention is lacking (Continuation of item 2 of first sheet)
This international Searching Authority found multiple inventions in this international application, as follows:
see additional sheet
As all required additional search fees were timely paid by the applicant, this International Search Report covers all searchable claims.
2. As all searchable claims could be searched without effort justifying an additional fee, this Authority did not invite payment of any additional fee.
As only some of the required additional search fees were timely paid by the applicant, this International Search Report covers only those claims for which fees were paid, specifically claims Nos.:
4. No required additional search fees were timely paid by the applicant. Consequently, this International Search Report is restricted to the invention first mentioned in the claims; it is covered by claims Nos.:
Remark on Protest  The additional search fees were accompanied by the applicant's protest.  X  No protest accompanied the payment of additional search fees.

### FURTHER INFORMATION CONTINUED FROM PCT/ISA/ 210

This International Searching Authority found multiple (groups of) inventions in this international application, as follows:

1. Claims: 1-15

A method of forming a microelectronic package by encapsulating one or several microelectronic die(s) with an encapsulation material and contacting the dies by a laminated interconnect layer.

2. Claims: 16-31

A method of soldering one or several microelectronic die(s) to a heat sink.

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